

LTM4675 - BGA-PBF 108LD 16mm X 11.9mm X 3.51mm (TABLE OF MATERIAL DECLARATION)									
The LTM4675 is RoHS compliant per EU RoHS Directive 2003/95/EC.									
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)									
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)		
1	Substrate	Circuit Board	0.2297	Barium Compounds	7727-43-7	0.00168	0.73		
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1	0.06407	27.89		
					1156-51-0/9003-36-5/21645-51-2				
					*non-disclosure				
				Copper Metal	7440-50-8	0.10569	46.01		
				Copper Compounds	147-14-8	0.00001	0.01		
				**Ecotoxic substances	7440-38-2	0.00002	0.01		
					7440-28-0				
				Gold metal or alloy	7440-57-5	0.00044	0.19		
				Nickel	7440-02-0	0.00331	1.44		
				Zinc	7440-66-6	0.00021	0.09		
				Continuous Filament Fiber Glass	65997-17-3	0.05038	21.93		
				Acrylic Resin	*non-disclosure	0.00319	1.39		
				Epoxy Resin	*non-disclosure	0.00008	0.04		
				Chromium(III) oxide	1308-38-9	0.00001	0.00		
				Silica amorphous	7631-86-9	0.00012	0.05		
				Talc;not containing fibers like asbestos	14807-96-6	0.00019	0.08		
				Aromatic carbonyl compounds	non-disclosure	0.00018	0.08		
				Cyanoguanidine	461-58-5	0.00000	0.00		
				Calcium caobonate	471-34-1	0.00002	0.01		
				Amine compounds	*non-disclosure	0.00003	0.01		
				Leveling agent and others	*non-disclosure	0.00008	0.03		
2	Solder Paste	Alloy	0.3656	Sn	7440-31-5	0.34736	95.00		
				Sb	7440-36-0	0.01828	5.00		
3	Passive/Active Components		0.3665	Iron Powder (Fe)	7439-89-6	0.26929	73.48		
				Copper (Cu)	7440-50-8	0.07341	20.03		
				Nickel (Ni)	7440-02-0	0.00285	0.78		
				Tin (Sn)	7440-31-5	0.00282	0.77		
				Ceramic (Ba) Compounds	12047-27-7	0.01813	4.95		
4	FC-DFN	-	0.1434	-	-	-	-		
	Chip	Silicon		Silicon	7440-21-3	0.00198	1.38		
	Clip	Copper alloy		Copper	7440-50-8	0.01578	11.01		
				Iron	7439-89-6	0.00039	0.27		
				Zinc	7440-66-6	0.00002	0.02		
	Die & Clip Attach	Epoxy Resin		Lead	7439-92-1	0.00368	2.57		
				Silver	7440-22-4	0.00010	0.07		
				Tin	7440-31-5	0.00020	0.14		
	Encapsulation	Epoxy Resin		Carbon Black	1333-86-4	0.00028	0.20		
				Epoxy Resin	29690-82-2	0.00142	0.99		
				Phenolic resin	9003-35-4	0.00142	0.99		
				Silica, vitreous	60676-86-0	0.02534	17.67		
	Lead Frame	Copper alloy		Copper	7440-50-8	0.04150	28.94		
				Iron	7439-89-6	0.00097	0.68		
				Zinc	7440-66-6	0.00005	0.04		
				Tin	7440-31-5	0.05020	35.01		
	Wire Bond	gold wire		Gold	7440-57-5	0.00005	0.03		
	5	Solder Ball		SAC305	0.2421	Sn	7440-31-5	0.23366	96.50
						Ag	7440-22-4	0.00726	3.00
						Cu	7440-50-8	0.00121	0.50
6	Encapsulation	Epoxy Resin	0.3204	Fused Silica	60676-86-0	0.24735	77.20		
				Epoxy Resin	non-disclosure	0.02852	8.90		
				Phenol Resin	non-disclosure	0.02852	8.90		
				Crytalline Silica	14808-60-7	0.00961	3.00		
				Carbon Black	1333-86-4	0.00160	0.50		
				Metal Hydroxide	non-disclosure	0.00481	1.50		
Total Package Weight			1.6678						

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts